

## C09G

### POLISHING COMPOSITIONS (French polish [C09F 11/00](#)); SKI WAXES

#### Definition statement

*This place covers:*

- Polishing compositions containing abrasives or grinding agents as well as polishing compositions based on aqueous dispersions, such as chemical mechanical polishing slurries for polishing semi conductors.
- Polishing compositions based on wax -this includes compositions based on mixtures of wax and natural or synthetic resins- and polishing compositions based on non-waxy substances, e. g. natural or synthetic resins.
- Ski waxes

#### References

##### Limiting references

*This place does not cover:*

Coating compositions based on oil, fats or waxes or derivatives thereof	<a href="#">C09D 191/00</a>
Coating compositions based on natural resins or derivatives thereof	<a href="#">C09D 193/00</a>
French polish	<a href="#">C09F 11/00</a>
Detergents	<a href="#">C11D</a>
Cleaning compositions for semi conductor devices	<a href="#">H10P 70/00</a>

##### Informative references

*Attention is drawn to the following places, which may be of interest for search:*

Grinding; Polishing machines and processes	<a href="#">B24B</a>
Compositions of macromolecular compounds	<a href="#">C08L</a>
Compositions of oils, fats or waxes or derivatives thereof	<a href="#">C08L 91/00</a>
Compositions of natural resins or derivatives thereof	<a href="#">C08L 93/00</a>
Abrasive powders, suspension and pastes for polishing	<a href="#">C09K 3/1454</a>
Chemical polishing of metals	<a href="#">C23F</a>
Cleaning or de-greasing of metallic material by chemical methods	<a href="#">C23G</a>
Manufacture of semiconductor devices, polishing	<a href="#">H10P 52/00</a>
Manufacture of semiconductor devices, chemical mechanical polishing	<a href="#">H10P 52/402</a>
Manufacture of semiconductor devices, deposition of non-insulating layers on insulating layers, chemical mechanical polishing thereof	<a href="#">H10P 52/403</a>
Mirror polishing of wafers	<a href="#">H10P 90/129</a>
Manufacture of semiconductor devices, planarisation of the insulating layers	<a href="#">H10P 95/06</a>
Manufacture of semiconductor devices, planarisation of conductors	<a href="#">H10W 20/062</a>

## Synonyms and Keywords

*In patent documents, the following abbreviations are often used:*

CMP	Chemical Mechanical Polishing
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## C09G 1/00

**Polishing compositions (French polish [C09F 11/00](#); detergents [C11D](#))**

### Definition statement

*This place covers:*

Polishing compositions containing abrasives or grinding agents; aqueous compositions and other polishing compositions based on wax or on non-waxy substances.

### References

#### Limiting references

*This place does not cover:*

French polish	<a href="#">C09F 11/00</a>
Abrasives as such	<a href="#">C09K 3/14</a>
Detergents	<a href="#">C11D</a>

#### Informative references

*Attention is drawn to the following places, which may be of interest for search:*

Abrasive powders, suspension and pastes for polishing	<a href="#">C09K 3/1463</a>
Manufacture of semiconductor devices, polishing	<a href="#">H10P 14/38</a>
Manufacture of semiconductor devices, chemical mechanical polishing	<a href="#">H10P 52/402</a>
Manufacture of semiconductor devices, deposition of non-insulating layers on insulating layers, chemical mechanical polishing thereof	<a href="#">H10P 52/403</a>
Manufacture of semiconductor devices, dielectric removal step	<a href="#">H10P 95/062</a>
Manufacture of semiconductor devices, planarisation of conductors	<a href="#">H10W 20/062</a>

### Special rules of classification

Abrasive free Chemical Mechanical Polishing (CMP) compositions are classified in [C09G 1/04](#). All other CMP compositions are classified in [C09G 1/02](#).

### Glossary of terms

*In this place, the following terms or expressions are used with the meaning indicated:*

CMP	Chemical Mechanical Polishing
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**C09G 3/00****Ski waxes****Definition statement**

*This place covers:*

Ski waxes.

**References*****Informative references***

*Attention is drawn to the following places, which may be of interest for search:*

Apparatus for waxing or dewaxing	<a href="#">A63C 11/08</a>
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